

CLAIMS

1. A process for producing resin-coated metal particles, the process comprising the steps of: coating surfaces of metal particles with silica; allowing a polymerizable group to adsorb onto the surfaces of the silica-coated metal particles by the use of a silane coupling agent; and coating the surfaces of the silica-coated metal particles with a polymeric resin by mixing the metal particles to which the polymerizable groups adsorb, a polymerizable monomer, a polymerization initiator, and a dispersant to polymerize the polymerizable monomer and the polymerizable groups.

2. The process for producing the resin-coated metal particles according to claim 1, the process further comprising a step of: melting the polymeric resin at a temperature higher than the melting point of the polymeric resin and then rapidly cooling the polymeric resin.

3. The process for producing the resin-coated metal particles according to claim 1 or 2, wherein the resin-coated metal particles are toner for forming a circuit.

4. The process for producing the resin-coated metal particles according to any one of claims 1 to 3, wherein the

metal particles are copper particles.

5. A resin-coated metal particle comprising: a core including a metal particle; a silica layer covering the surface of the core; and a resin layer covering the silica layer.

6. The resin-coated metal particle according to claim 5, wherein the particle comprises one metal selected from copper, silver, nickel, and silver-palladium.

7. The resin-coated metal particle according to claim 5 or 6, wherein the surface of the particle is subjected to oxidation.

8. Toner for forming a circuit, comprising: a resin-coated metal particle according to any one of claims 5 to 7.